

AMENDMENTS TO THE CLAIMS

Please rewrite the claims as follows:

1. (Previously presented) An exposure method of exposing a predetermined pattern formed on a reticle to a substrate through a projection optical system while the reticle and the substrate are scanned in synchronous with each other, comprising:

a measuring step of measuring a position tilt of an image plane of the projection optical system at a plurality of different measurement positions with respect to in a direction in which the reticle and the substrate are scanned; and

a correcting step of correcting a tilt ~~the tilt~~ of the image plane of the projection optical system based on measurements ~~measurement~~ obtained by the measuring step,

wherein, in the measuring step, the position tilt of the image plane is measured by detecting a light through the projection optical system.

2. (Original) An exposure method according to claim 1, wherein the plurality of measurement positions in the measuring step are at least three positions which are not arranged on a straight line.

3. (Original) An exposure method according to claim 1, wherein the correcting step includes correction of a tilt of the image plane of the projection optical system in the scanning direction in accordance with the measurements obtained by the measuring step.

4. (Original) An exposure method according to claim 1, further comprising:
a step of calculating a curvature of the image plane of the projection optical system from the measurements obtained by the measuring step.

5. (Original) An exposure method according to claim 1, wherein the correcting step includes adjustment of at least one of a position of the substrate and the projection

optical system to reduce the tilt of the image plane of the projection optical system, which is caused from the predetermined pattern.

6. (Original) An exposure method according to claim 1, wherein the correcting step includes at least one of drive of an optical element included in the projection optical system in an optical axis direction of the projection optical system and decentering of the optical element about the optical axis direction of the projection optical system, and tilting of the optical element with respect to the optical axis direction of the projection optical system.

7. (Original) An exposure method according to claim 1, wherein at least one of the plurality of measurement positions are located outside an area which is irradiated with exposure light at a time of exposure.

8. (Original) An exposure method according to claim 7, wherein at least one of the plurality of measurement positions is located outside an area which is irradiated with the exposure light in the scanning direction.

9-10. (Canceled)

11. (Previously presented) An exposure apparatus for exposing a predetermined pattern formed on a reticle to a substrate through a projection optical system while the reticle and the substrate are scanned in synchronous with each other, comprising:

a measuring mechanism for measuring a position tilt of an image plane of the projection optical system at a plurality of measurement positions different from each other with respect to in a direction in which the reticle and the substrate are scanned; and

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a correcting mechanism for correcting a tilt ~~the tilt~~ of the image plane of the projection optical system based on measurements ~~measurement~~ obtained by the measuring mechanism,

wherein the position tilt of the image plane is measured by detecting a light through the projection optical system.

12. (Original) A device manufacturing method, comprising:
- a step of applying a photosensitive agent to a substrate;
 - an exposing step of exposing the substrate by the exposure method according to claim 1; and
 - a developing step of developing the exposed substrate.

13. (Cancelled)

14. (Original) A device manufacturing method, comprising:
- a step of applying a photosensitive agent to a substrate;
 - an exposing step of exposing the substrate by the exposure apparatus according to claim 11; and
 - a developing step of developing the exposed substrate.